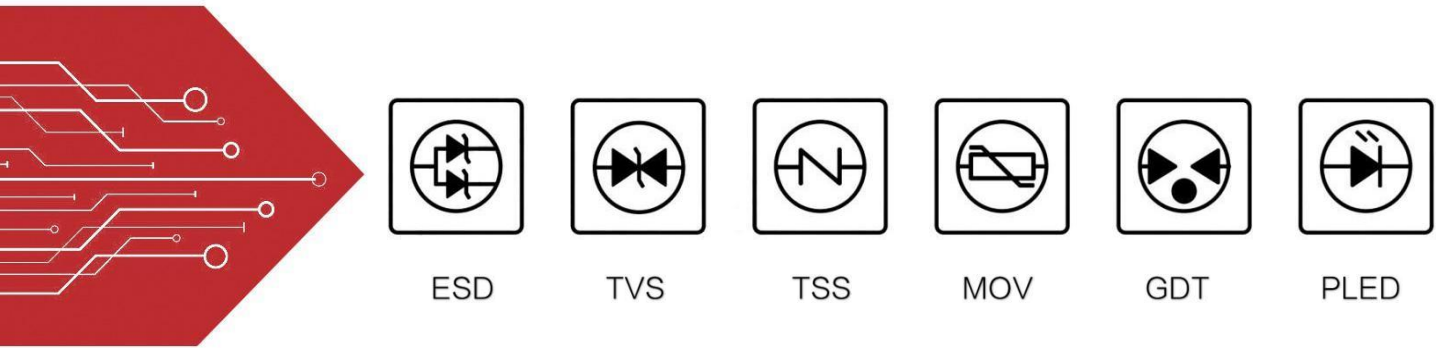
MSKSEMI
SEMICONDUCTOR



Product data sheet

Features

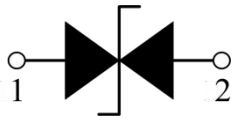
80 Watts peak pulse power (tp = 8/20μs)
Transient protection for high speed data lines to
IEC 61000-4-2 (ESD) ±15kV (air), ±8kV (contact)
IEC 61000-4-4 (EFT) 40A (5/50ns)
Working voltages : 5V
Protects One Power or I/O Port
Low operating and clamping voltages
Solid-state silicon avalanche technology

Pin Description



DFN1006P2X

Schematic Diagram



Applications

Notebooks, Desktops, Servers and Video Graphics Cards
USB Power & Data Line Protection
Monitors and Flat Panel Displays
I²C Bus Protection
Portable Instrumentation
Set Top Box

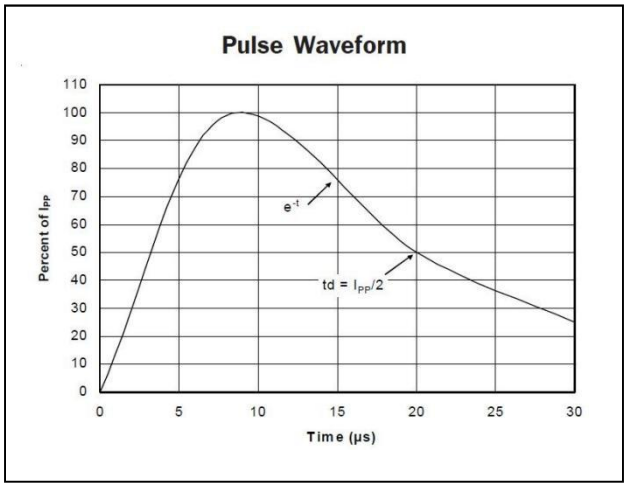
Maximum Rating @ Ta=25℃ unless otherwise specified

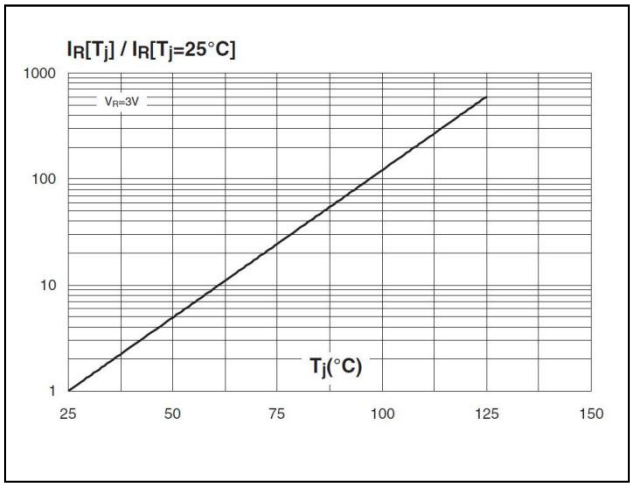
Symbol	Parameter	Ratings	Units
P_{PK}	Peak Pulse Power (tp = 8/20μs)	80	Watts
T_L	Lead Soldering Temperature	260(10sec.)	℃
T_J	Operating Temperature	-55 to +125	℃
T_{STG}	Storage Temperature	-55 to +150	℃

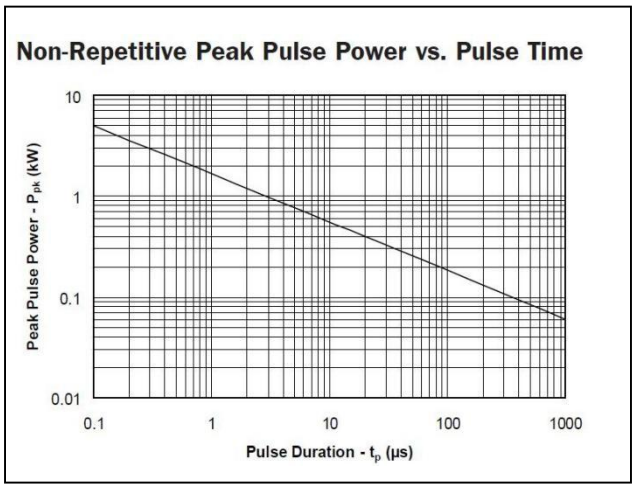
Electrical Characteristics@ Ta=25℃ unless otherwise

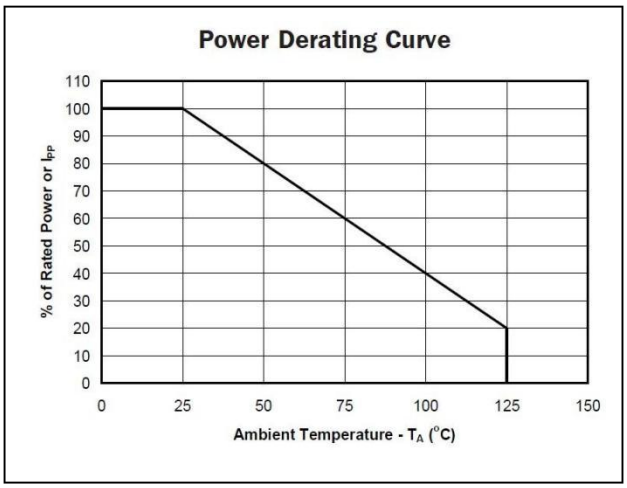
P/N	V_{RWM} @I_R		V_{BR}@ImA	V_C@1	V_C@I_{PP}		C_J
	V	**μA**	V	V	V	A	pF
		MAX	MIN	MAX	MAX		TYP
AZ5325-01F.R7G	5	1	5.8	11.8	15	5	2.5

Typical Characteristics@ Ta=25℃ unless otherwise specified

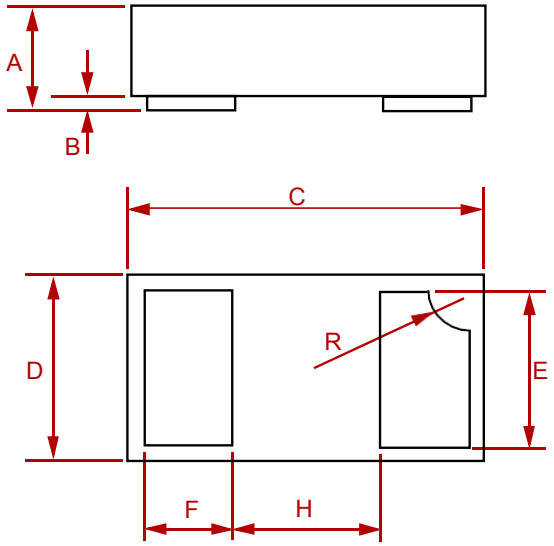






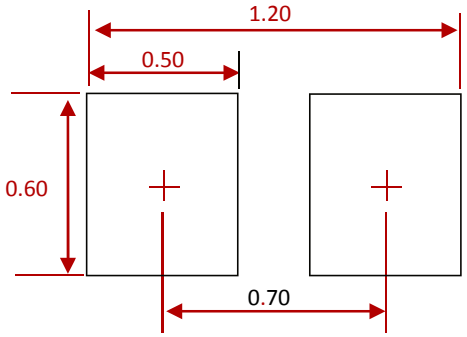


PACKAGE MECHANICAL DATA



Dim	Inches		Millimeters	
	MIN	MAX	MIN	MAX
A	0.0125	0.02	0.32	0.52
B	0.000	0.002	0.00	0.05
C	0.037	0.043	0.95	1.080
D	0.022	0.027	0.55	0.680
E	0.016	0.024	0.40	0.60
F	0.008	0.012	0.20	0.30
H	0.015Typ.		0.40Typ.	
R	0.001	0.005	0.05	0.15

Suggested Pad Layout



NOTES:

1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
2. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY. CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR COMPANY'S MANUFACTURING GUIDELINES ARE MET.

REEL SPECIFICATION

P/N	PKG	QTY
AZ5325-01F.R7G	DFN1006P2X	12000

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